DATA SHEET

Part No.	AN41902A
Package Code No.	HQFP048-P-0707

Contents

AN41902A

Lens Motor Driver IC

■ Overview

The AN41902A is a four channels H-bridge driver IC which interface block consists of CMOS circuit.
The AN41902A consumes less-power than conventional drivers that use bipolar transistors.

■ Features

- Current feedback 64-step microstepping drive
- Motor control with a bidirectional 3-wire serial interface
- Possible to set the output current value, the pulse period, pulse count and possible to read excitation position information.

■ Applications

- Lens motor driver for digital cameras and digital camcorders
- Stepping motor drive

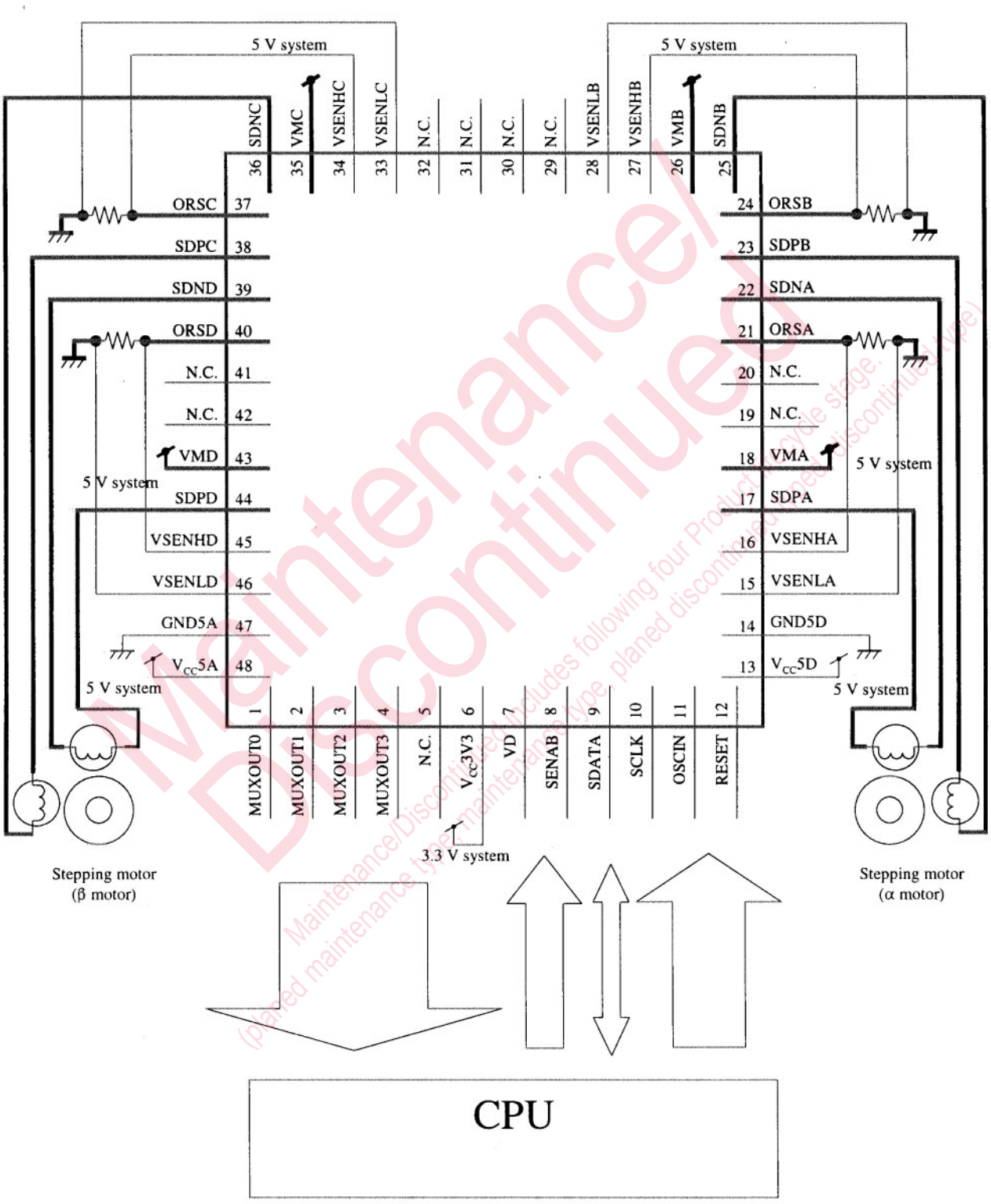
■ Package

- 48-pin plastic quad flat package (QFP type) with heat slug

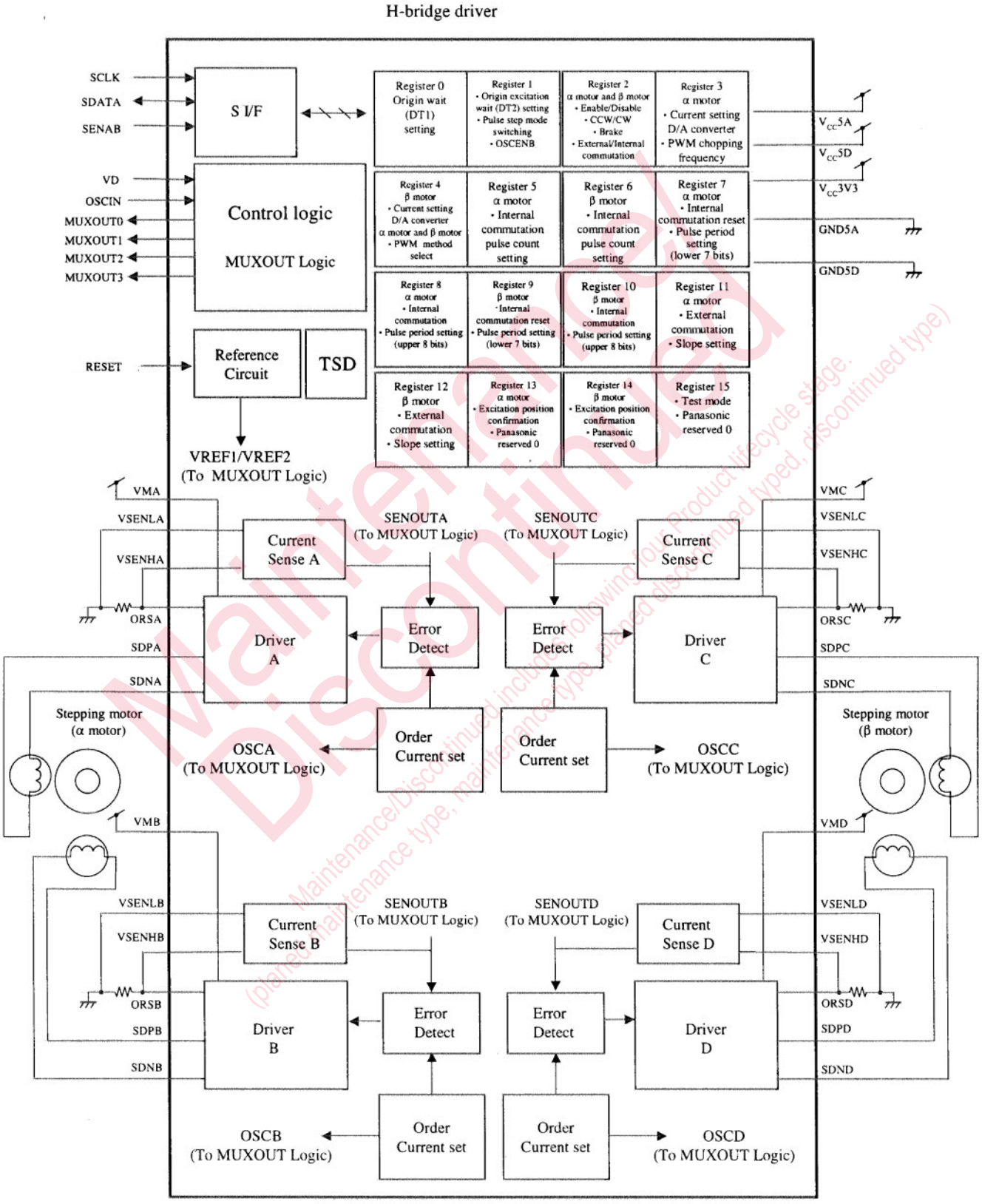
■ Type

- Silicon monolithic bipolar IC

■ Application Circuit Example



■ Block Diagram



■ Pin Descriptions

Pin No.	Pin name	Type	Description
1	MUXOUT0	O	Analog voltage monitor output 0
2	MUXOUT1	O	Analog voltage monitor output 1
3	MUXOUT2	O	Analog voltage monitor output 2
4	MUXOUT3	O	Analog voltage monitor output 3
5	N.C.	—	N.C.
6	V_{CC}3V3	—	3.3 V digital power supply
7	VD	I	Video sync signal input
8	SENAB	I	Serial port select (Active low)
9	SDATA	I/O	Serial port input data
10	SCLK	I	Serial port input clock
11	OSCIN	I	Control oscillator input
12	RESET	I	Reset signal input
13	V_{CC}5D	—	5 V digital power supply
14	GND5D	—	Digital ground
15	VSENLA	I	Channel A – input of sense amplifier
16	VSENHA	I	Channel A + input of sense amplifier
17	SDPA	O	Channel A + output of H-bridge driver
18	VMA	—	Channel A motor power supply
19	N.C.	—	N.C.
20	N.C.	—	N.C.
21	ORSA	O	Channel A motor current detection
22	SDNA	O	Channel A – output of H-bridge driver
23	SDPB	O	Channel A + output of H-bridge driver
24	ORSB	O	Channel B motor current detection
25	SDNB	O	Channel B + output of H-bridge driver
26	VMB	—	Channel B motor power supply
27	VSENHB	I	Channel B + input of sense amplifier
28	VSENLB	I	Channel B – input of sense amplifier
29	N.C.	—	N.C.
30	N.C.	—	N.C.
31	N.C.	—	N.C.
32	N.C.	—	N.C.
33	VSENLC	I	Channel C – input of sense amplifier
34	VSENHC	I	Channel C + input of sense amplifier
35	VMC	—	Channel C motor power supply

■ Pin Descriptions (continued)

Pin No.	Pin name	Type	Description
36	SDNC	O	Channel C – output of H-bridge driver
37	ORSC	O	Channel C motor current detection
38	SDPC	O	Channel C + output of H-bridge driver
39	SDND	O	Channel D – output of H-bridge driver
40	ORSD	O	Channel D motor current detection
41	N.C.	—	N.C.
42	N.C.	—	N.C.
43	VMD	—	Channel D motor power supply
44	SDPD	O	Channel D + output of H-bridge driver
45	VSENHD	I	Channel D + input of sense amplifier
46	VSENLD	I	Channel D – input of sense amplifier
47	GND5A	—	Analog ground
48	V_{CC}5A	—	5 V analog power supply

■ Absolute Maximum Ratings

A No.	Parameter	Symbol	Rating	Unit	Notes
1	Control block supply voltage	V_{CC}3V3	– 0.3 to +4.5	V	*1
2	Motor control block supply voltage	V_{CC}5A	– 0.3 to +6	V	*1
3	Motor drive block supply voltage	V_{CC}5D VM(A,B,C,D)	– 0.3 to +6	V	*1
4	Power dissipation	P_D	354.6	mW	*2
5	Operating ambient temperature	T_{opr}	–10 to +75	°C	*3
6	Storage temperature	T_{stg}	–55 to +125	°C	*3
7	H-bridge drive current	$I_{M(CD)}$	±0.25	A/ch	
8	Instantaneous H-bridge drive current	$I_{M(pulse)}$	±0.4	A/ch	
9	Digital signal input voltage	V_{IN}	– 0.3 to V_{CC}3V3 + 0.3	V	

Notes) *1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.
*2 : The power dissipation shown is the value at T_a = 85°C for the independent (unmounted) IC package with out a heat sink.
*3 : Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for T_a = 25°C.

■ Operating supply voltage range

Parameter	Symbol	Rangs			Unit	Notes
		Min	Typ	Max		
Supply voltage range	V_{CC}3V3	2.7	3.3	3.9	V	
	V_{CC}5A	3.0	5.0	5.5		
	V_{CC}5D VM(A,B,C,D)	3.0	5.0	5.5		

Note) * : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

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